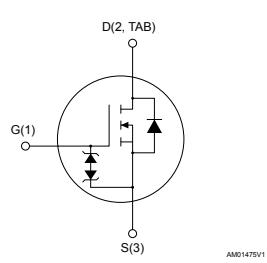
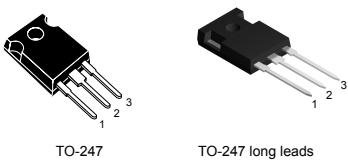


N-channel 600 V, 60 mΩ typ., 38 A MDmesh™ DM6 Power MOSFETs
in TO-247 and TO-247 long leads packages

Features



Order code	V _{DS}	R _{DS(on) max.}	I _D
STW65N60DM6	600 V	71 mΩ	38 A
STWA65N60DM6			

- Fast-recovery body diode
- Lower R_{DS(on)} per area vs previous generation
- Low gate charge, input capacitance and resistance
- 100% avalanche tested
- Extremely high dv/dt ruggedness
- Zener-protected

Applications

- Switching applications

Description

These high-voltage N-channel Power MOSFETs are part of the MDmesh™ DM6 fast-recovery diode series. Compared with the previous MDmesh fast generation, DM6 combines very low recovery charge (Q_{rr}), recovery time (t_{rr}) and excellent improvement in R_{DS(on)} per area with one of the most effective switching behaviors available in the market for the most demanding high-efficiency bridge topologies and ZVS phase-shift converters.



Product status link	
STW65N60DM6	
STWA65N60DM6	

Product summary	
Order code	STW65N60DM6
Marking	65N60DM6
Package	TO-247
Packing	Tube
Order code	STWA65N60DM6
Marking	65N60DM6
Package	TO-247 long leads
Packing	Tube

1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{GS}	Gate-source voltage	± 25	V
I_D	Drain current (continuous) at $T_C = 25^\circ\text{C}$	38	A
I_D	Drain current (continuous) at $T_C = 100^\circ\text{C}$	24	A
$I_D^{(1)}$	Drain current (pulsed)	140	A
P_{TOT}	Total dissipation at $T_C = 25^\circ\text{C}$	250	W
$dv/dt^{(2)}$	Peak diode recovery voltage slope	50	V/ns
$dv/dt^{(3)}$	MOSFET dv/dt ruggedness	100	V/ns
T_{STG}	Storage temperature range	-55 to 150	$^\circ\text{C}$
T_J	Operating junction temperature range		

1. Pulse width limited by safe operating area.
2. $I_{SD} \leq 38 \text{ A}$, $di/dt \leq 900 \text{ A}/\mu\text{s}$; $V_{DS}(\text{peak}) < V_{(BR)DSS}$, $V_{DD} = 400 \text{ V}$.
3. $V_{DS} \leq 480 \text{ V}$.

Table 2. Thermal data

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction-case	0.5	$^\circ\text{C}/\text{W}$
$R_{thj-amb}$	Thermal resistance junction-ambient	50	$^\circ\text{C}/\text{W}$

Table 3. Avalanche characteristics

Symbol	Parameter	Value	Unit
I_{AR}	Avalanche current, repetitive or not repetitive (pulse width limited by T_{jmax})	6	A
E_{AS}	Single pulse avalanche energy (starting $T_j = 25^\circ\text{C}$, $I_D = I_{AR}$; $V_{DD} = 50 \text{ V}$)	900	mJ

2

Electrical characteristics

$T_C = 25^\circ\text{C}$ unless otherwise specified

Table 4. On/off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(\text{BR})\text{DSS}}$	Drain-source breakdown voltage	$V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}$	600			V
I_{DSS}	Zero gate voltage drain current	$V_{GS} = 0 \text{ V}, V_{DS} = 600 \text{ V}$			5	μA
		$V_{GS} = 0 \text{ V}, V_{DS} = 600 \text{ V}, T_C = 125^\circ\text{C}^{(1)}$			100	
I_{GSS}	Gate-body leakage current	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 25 \text{ V}$			± 5	μA
$V_{GS(\text{th})}$	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	3.25	4	4.75	V
$R_{\text{DS(on)}}$	Static drain-source on resistance	$V_{GS} = 10 \text{ V}, I_D = 19 \text{ A}$		60	71	$\text{m}\Omega$

1. Defined by design, not subject to production test.

Table 5. Dynamic characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	$V_{DS} = 100 \text{ V}, f = 1 \text{ MHz}, V_{GS} = 0 \text{ V}$	-	2500	-	pF
C_{oss}	Output capacitance		-	125	-	
C_{rss}	Reverse transfer capacitance		-	4	-	
$C_{oss\ eq.}^{(1)}$	Equivalent output capacitance	$V_{DS} = 0$ to $480 \text{ V}, V_{GS} = 0 \text{ V}$	-	204	-	
R_G	Intrinsic gate resistance	$f = 1 \text{ MHz}, I_D = 0 \text{ A}$	-	1.7	-	Ω
Q_g	Total gate charge	$V_{DD} = 480 \text{ V}, I_D = 38 \text{ A}, V_{GS} = 0$ to 10 V (see Figure 14. Test circuit for gate charge behavior).	-	54	-	nC
Q_{gs}	Gate-source charge		-	16	-	
Q_{gd}	Gate-drain charge		-	22	-	

1. $C_{oss\ eq.}$ is defined as a constant equivalent capacitance giving the same charging time as C_{oss} when V_{DS} increases from 0 to 80% V_{DSS} .

Table 6. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 300 \text{ V}, I_D = 19 \text{ A}, R_G = 4.7 \Omega, V_{GS} = 10 \text{ V}$ (see Figure 15. Test circuit for inductive load switching and diode recovery times and Figure 18. Switching time waveform)	-	21	-	ns
t_r	Rise time		-	22	-	ns
$t_{d(off)}$	Turn-off delay time		-	56	-	ns
t_f	Fall time		-	9	-	ns

Table 7. Source drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain current		-		38	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-		140	A
$V_{SD}^{(2)}$	Forward on voltage	$V_{GS} = 0 \text{ V}, I_{SD} = 38 \text{ A}$	-		1.6	V
t_{rr}	Reverse recovery time	$I_{SD} = 38 \text{ A}, dI/dt = 100 \text{ A}/\mu\text{s},$ $V_{DD} = 60 \text{ V}$ (see Figure 15. Test circuit for inductive load switching and diode recovery times)	-	116	-	ns
Q_{rr}	Reverse recovery charge		-	0.58	-	μC
I_{RRM}	Reverse recovery current		-	10	-	A
t_{rr}	Reverse recovery time	$I_{SD} = 38 \text{ A}, dI/dt = 100 \text{ A}/\mu\text{s},$ $V_{DD} = 60 \text{ V}, T_J = 150 \text{ }^\circ\text{C}$ (see Figure 15. Test circuit for inductive load switching and diode recovery times)	-	208	-	ns
Q_{rr}	Reverse recovery charge		-	1.98	-	μC
I_{RRM}	Reverse recovery current		-	19	-	A

1. Pulse width is limited by safe operating area.
2. Pulsed: pulse duration = 300 μs , duty cycle 1.5%.

2.1 Electrical characteristics curves

Figure 1. Safe operating area

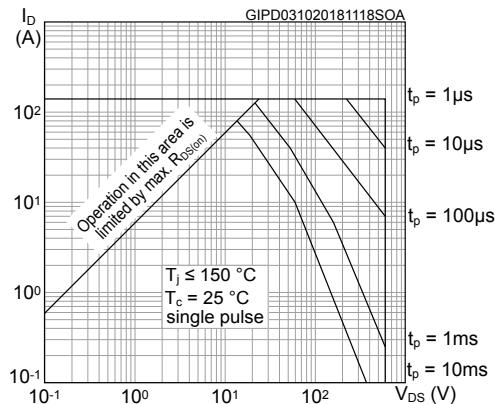


Figure 2. Thermal impedance

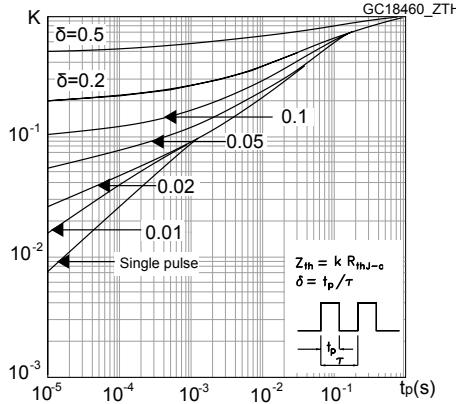


Figure 3. Output characteristics

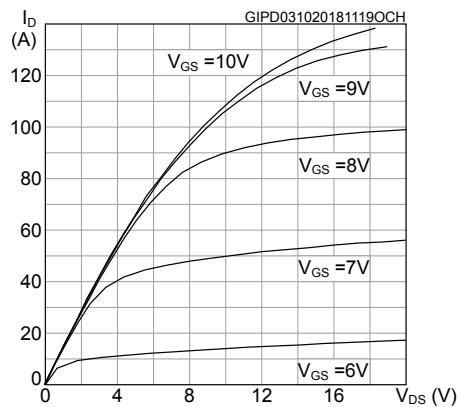


Figure 4. Transfer characteristics

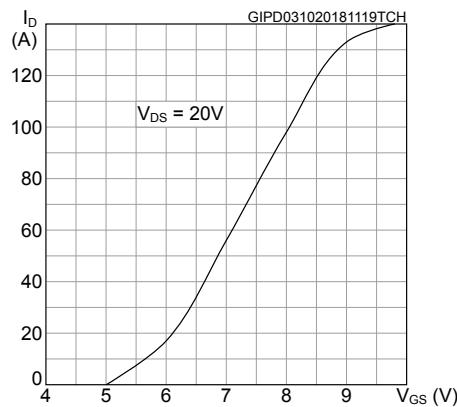


Figure 5. Static drain-source on resistance

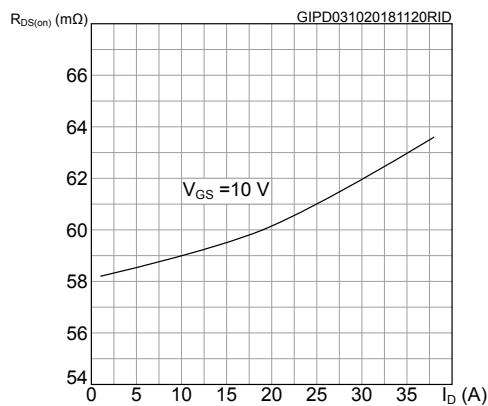


Figure 6. Gate charge vs gate-source voltage

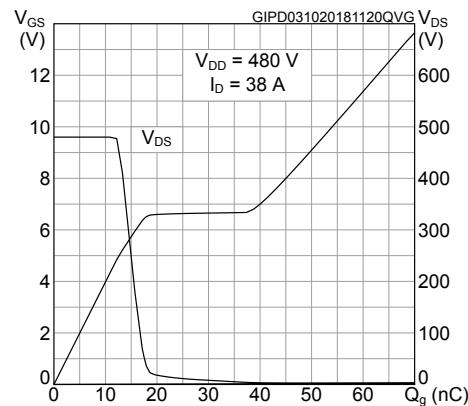
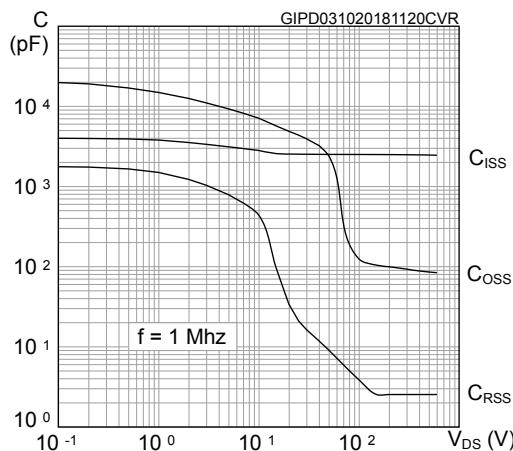
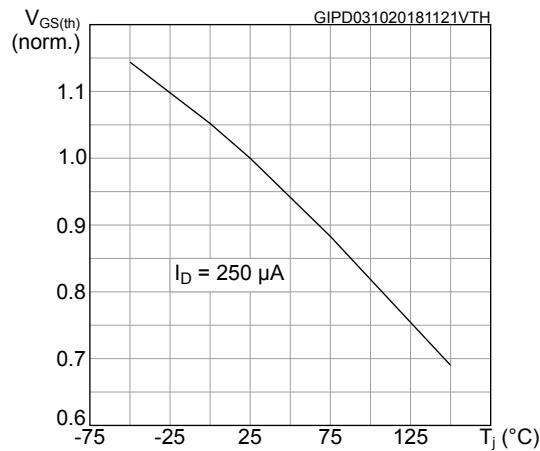
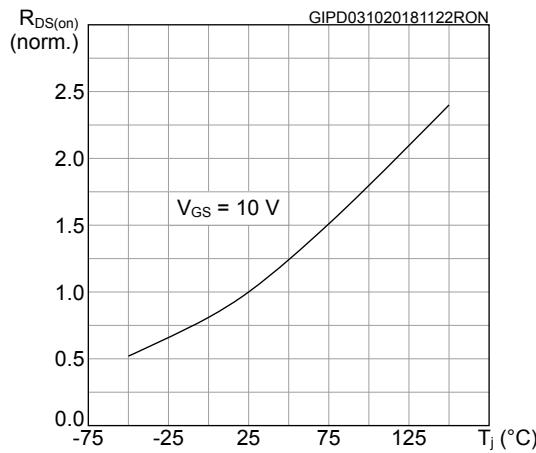
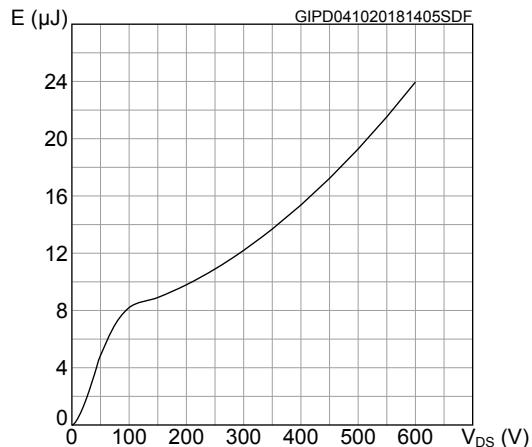
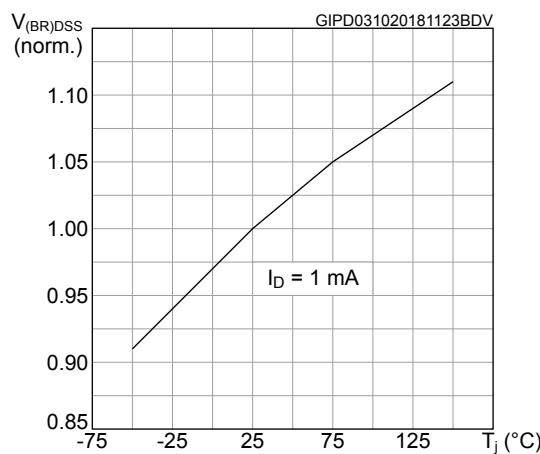
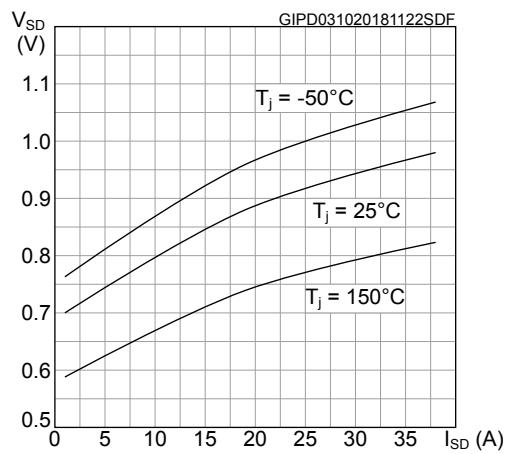
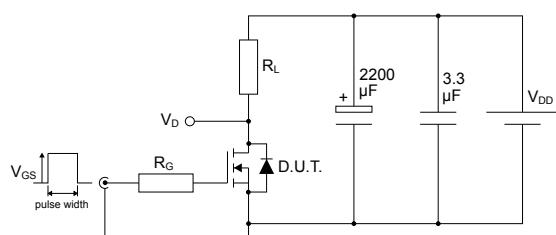


Figure 7. Capacitance variations

Figure 8. Normalized gate threshold voltage vs temperature

Figure 9. Normalized on resistance vs temperature

Figure 10. Coss stored energy vs VDS

Figure 11. Normalized $V_{(BR)DSS}$ vs temperature

Figure 12. Source-drain diode forward characteristic


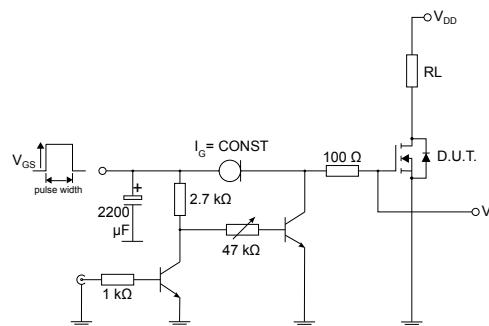
3 Test circuits

Figure 13. Test circuit for resistive load switching times



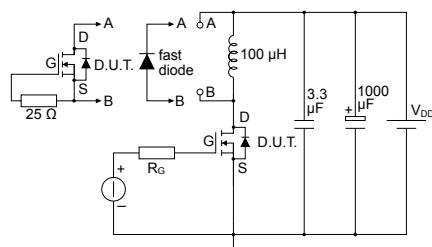
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Figure 14. Test circuit for gate charge behavior



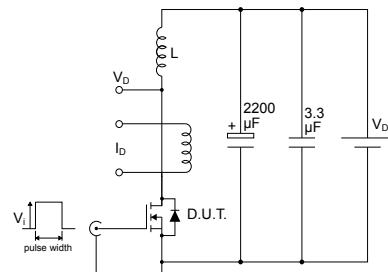
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Figure 15. Test circuit for inductive load switching and diode recovery times



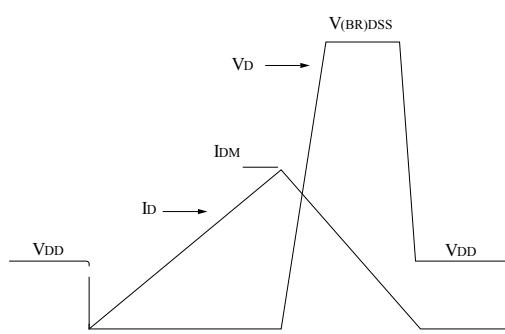
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Figure 16. Unclamped inductive load test circuit



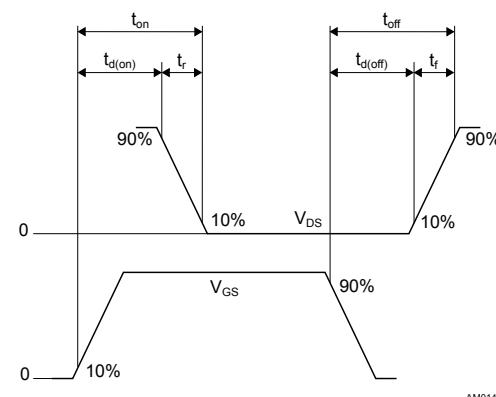
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Figure 17. Unclamped inductive waveform



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Figure 18. Switching time waveform



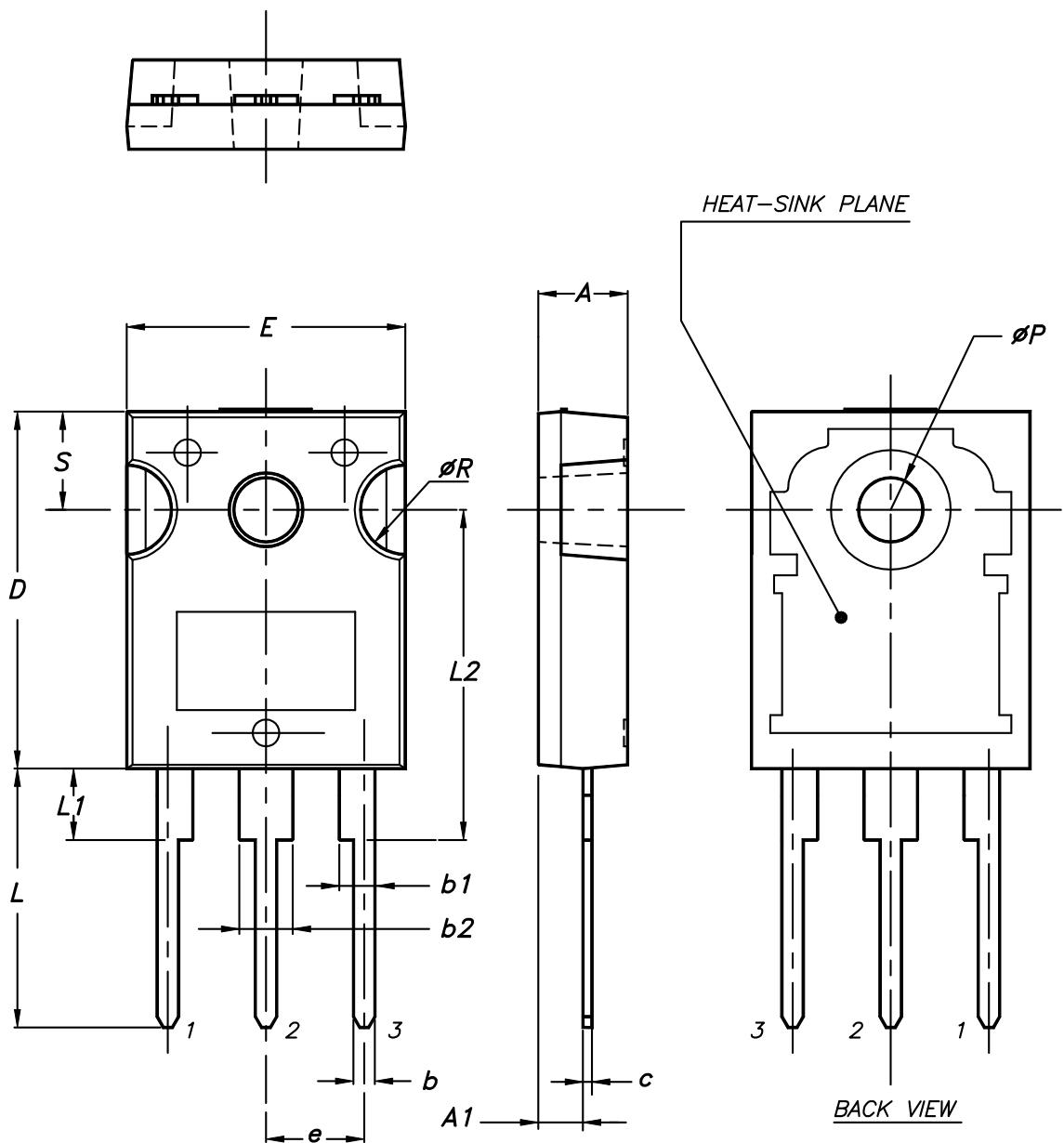
AM01473v1

4**Package information**

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

4.1 TO-247 package information

Figure 19. TO-247 package outline



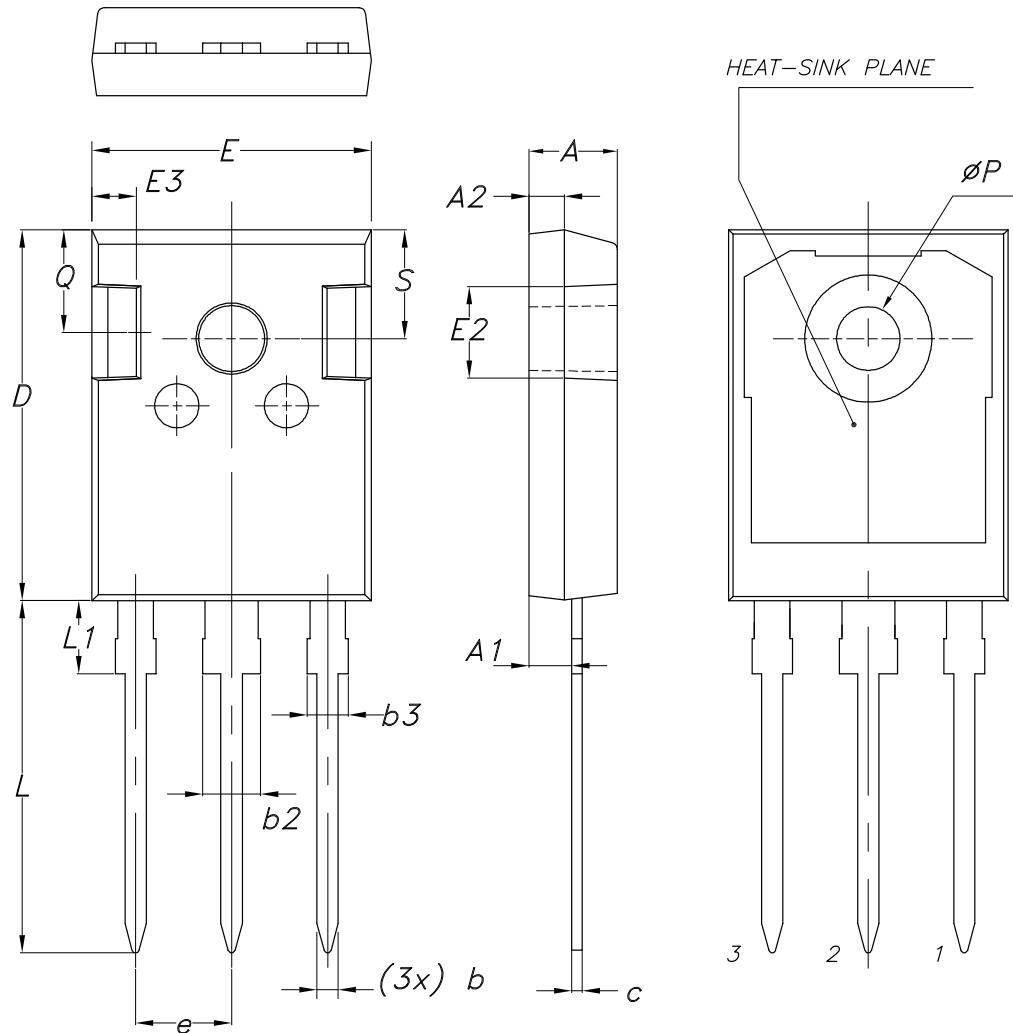
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Table 8. TO-247 package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.85		5.15
A1	2.20		2.60
b	1.0		1.40
b1	2.0		2.40
b2	3.0		3.40
c	0.40		0.80
D	19.85		20.15
E	15.45		15.75
e	5.30	5.45	5.60
L	14.20		14.80
L1	3.70		4.30
L2		18.50	
ØP	3.55		3.65
ØR	4.50		5.50
S	5.30	5.50	5.70

4.2 TO-247 long leads package information

Figure 20. TO-247 long leads package outline



8463846_2_F

Table 9. TO-247 long leads package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.90	5.00	5.10
A1	2.31	2.41	2.51
A2	1.90	2.00	2.10
b	1.16		1.26
b2			3.25
b3			2.25
c	0.59		0.66
D	20.90	21.00	21.10
E	15.70	15.80	15.90
E2	4.90	5.00	5.10
E3	2.40	2.50	2.60
e	5.34	5.44	5.54
L	19.80	19.92	20.10
L1			4.30
P	3.50	3.60	3.70
Q	5.60		6.00
S	6.05	6.15	6.25

Revision history

Table 10. Document revision history

Date	Version	Changes
02-Nov-2017	1	Initial release.
03-Oct-2018	2	<p>Removed maturity status indication from cover page. The document status is production data.</p> <p>Updated title and features in cover page.</p> <p>Updated Section 1 Electrical ratings, Section 2 Electrical characteristics.</p> <p>Added Section 2.1 Electrical characteristics curves.</p> <p>Minor text changes.</p>

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